

650V 10A Advanced N-Ch Power MOSFET

FEATURES

- High Voltage : $BV_{DSS}=650V(\text{Min.})$
- Low C_{rss} : $C_{rss}=16pF(\text{Typ.})$
- Low gate charge : $Q_g=35nC(\text{Typ.})$
- Low $R_{DS(on)}$: $R_{DS(on)}=0.85\Omega(\text{Max.})$

Marking Information

Row 1 : AP

Row 2 : Product Information

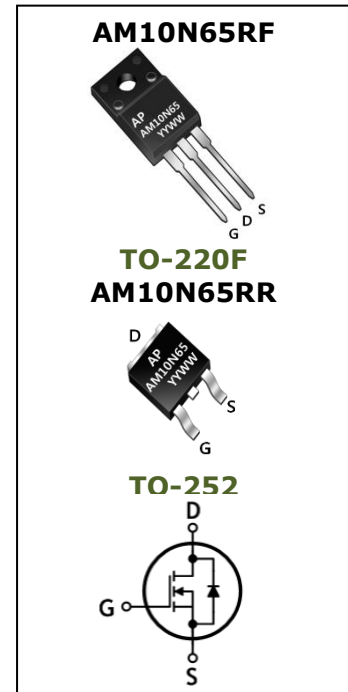
Row 3 : Date Code

- YY : Year Code

- WW : Week Code

Ordering Information

Part No	Package	Packing	Finish	Halogen	Packing Unit
AM10N65RF	TO-220F	Tube	Sn	Free	5,000ea
AM10N65RR	TO-252	Tape & Reel	Sn	Free	2,500ea



Maximum Ratings ($T_c=25^\circ\text{C}$, unless otherwise noted)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	650	V
Gate-source voltage	V_{GSS}	± 30	V
Drain current (DC)*	I_D	$T_c = 25^\circ\text{C}$	A
		$T_c = 100^\circ\text{C}$	
Drain current (Pulsed)*	I_{DM}	36	A
Power Dissipation	P_D	40	W
Avalanche current (Single) (Note 2)	I_{AS}	9	A
Single pulsed avalanche energy (Note 2)	E_{AS}	250	mJ
Avalanche current (Repetitive) (Note 1)	I_{AR}	9	A
Repetitive avalanche energy (Note 1)	E_{AR}	11.6	mJ
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55~150	

*Limited only maximum junction temperature

Thermal Characteristic

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 3.1	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 62.5	

Electrical Characteristics ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DS}	$I_D = 250\mu\text{A}$, $V_{GS} = 0$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D = 250\mu\text{A}$, $V_{DS} = V_{GS}$	2.0	-	4.0	V
Drain-source cut-off current	I_{DSS}	$V_{DS} = 650\text{V}$, $V_{GS} = 0\text{V}$	-	-	1	μA
Gate leakage current	I_{GSS}	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 30\text{V}$	-	-	± 100	nA
Drain-source on-resistance (Note 4)	$R_{DS(ON)}$	$V_{GS} = 10\text{V}$, $I_D = 4.5\text{A}$	-	0.72	0.85	Ω
Forward transfer conductance (Note 4)	g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 4.5\text{A}$	-	11	-	S
Input capacitance	C_{iss}	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$	-	2007	2550	pF
Output capacitance	C_{oss}		-	153	192	
Reverse transfer capacitance	C_{rss}		-	5.68	10	
Turn-on delay time (Note 3,4)	$T_{d(on)}$	$V_{DS} = 300\text{V}$, $I_D = 9\text{A}$, $R_G = 25\Omega$	-	23	-	ns
Rise time (Note 3,4)	T_r		-	69	-	
Turn-off delay time (Note 3,4)	$t_{d(off)}$		-	144	-	
Fall time (Note 3,4)	t_f		-	77	-	
Total gate charge (Note 3,4)	Q_g	$V_{DS} = 520\text{V}$, $V_{GS} = 10\text{V}$, $I_D = 9\text{A}$	-	35	57	nC
Gate-source charge (Note 3,4)	Q_{gs}		-	10	-	
Gate-drain charge (Note 3,4)	Q_g		-	9	-	

Source-Drain Diode Ratings and Characteristics ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

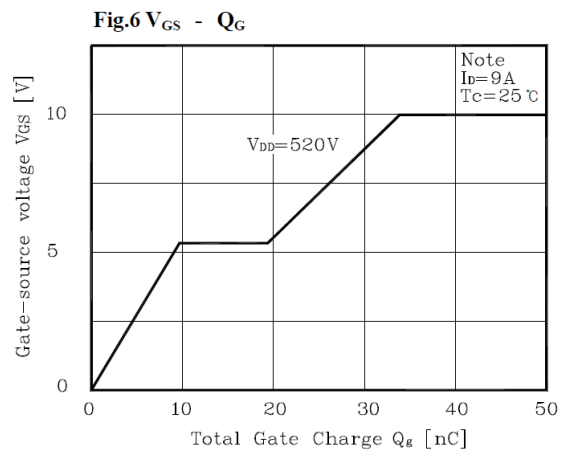
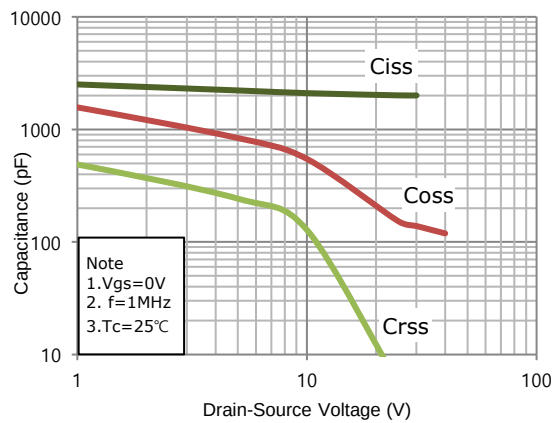
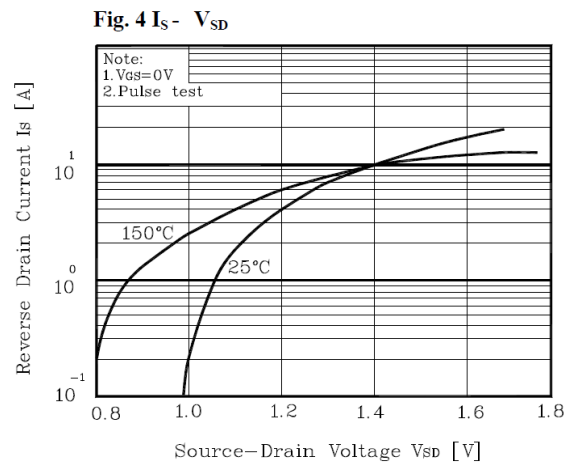
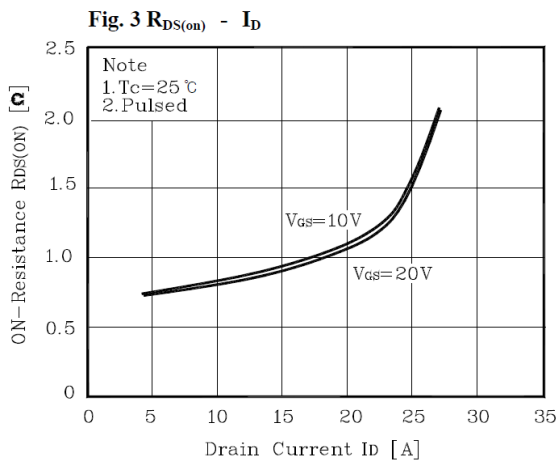
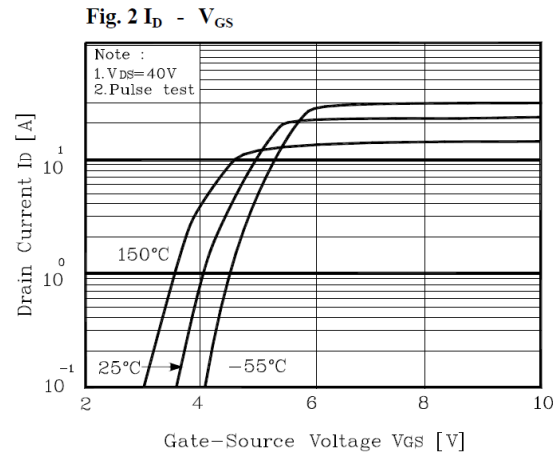
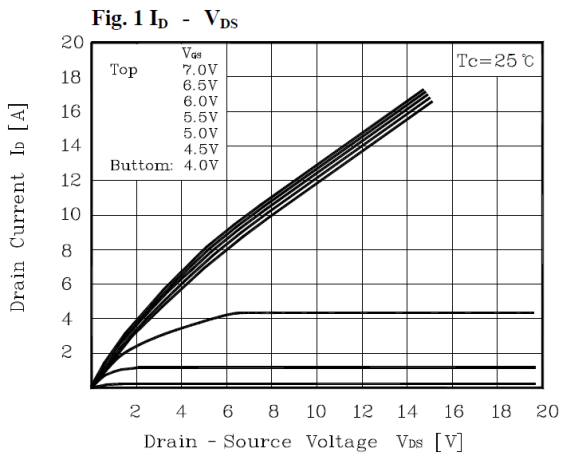
Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	9	A
Source current (Pulsed) (Note 1)	I_{SM}		-	-	36	A
Forward voltage (Note 4)	V_{SD}	$V_{GS} = 0\text{V}$, $I_S = 9\text{A}$	-	-	1.4	V
Reverse recovery time	t_{rr}	$I_S = 9\text{A}$, $V_{GS} = 0\text{V}$ $dI_F/dt = 100\text{A}/\mu\text{s}$	-	420	-	ns
Reverse recovery charge	Q_{rr}		-	4.2	-	μC

Note :

1. Repetitive rating : Pulse width limited by maximum junction temperature.
2. $L=5.7\text{mH}$, $I_{AS}=9\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
3. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
4. Essentially independent of operating temperature



Typical Electrical Characteristic



Typical Electrical Characteristic

Fig. 7 $V_{DS} - T_J$

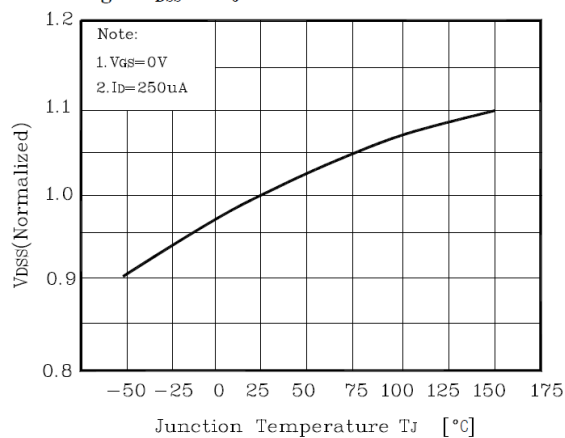


Fig.8 $R_{DS(on)} - T_J$

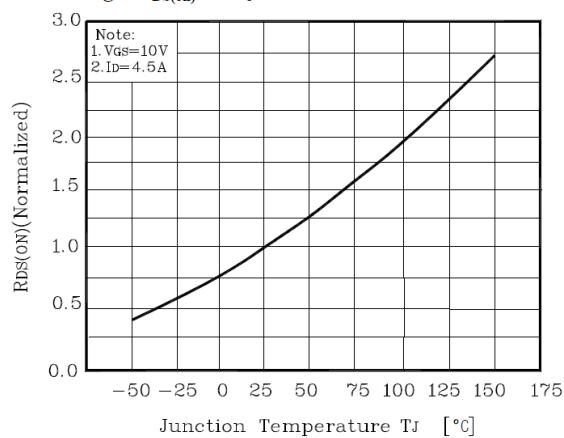


Fig. 9 $I_D - T_C$

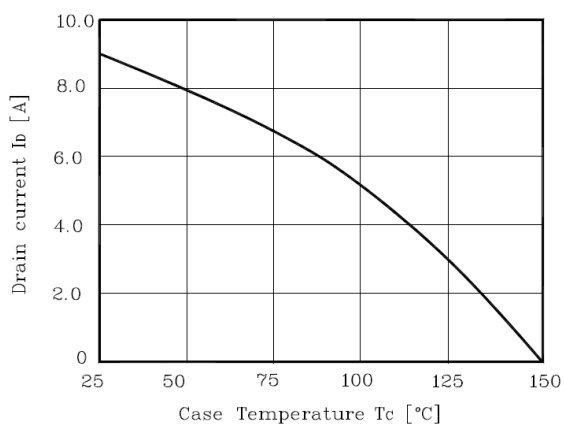


Fig. 10 Safe Operating Area

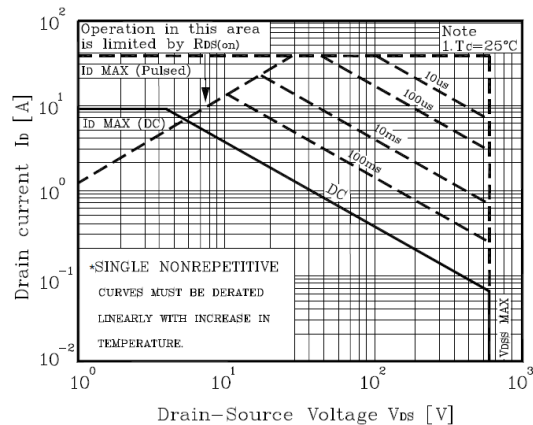


Fig. 11 Gate Charge Test Circuit & Waveform

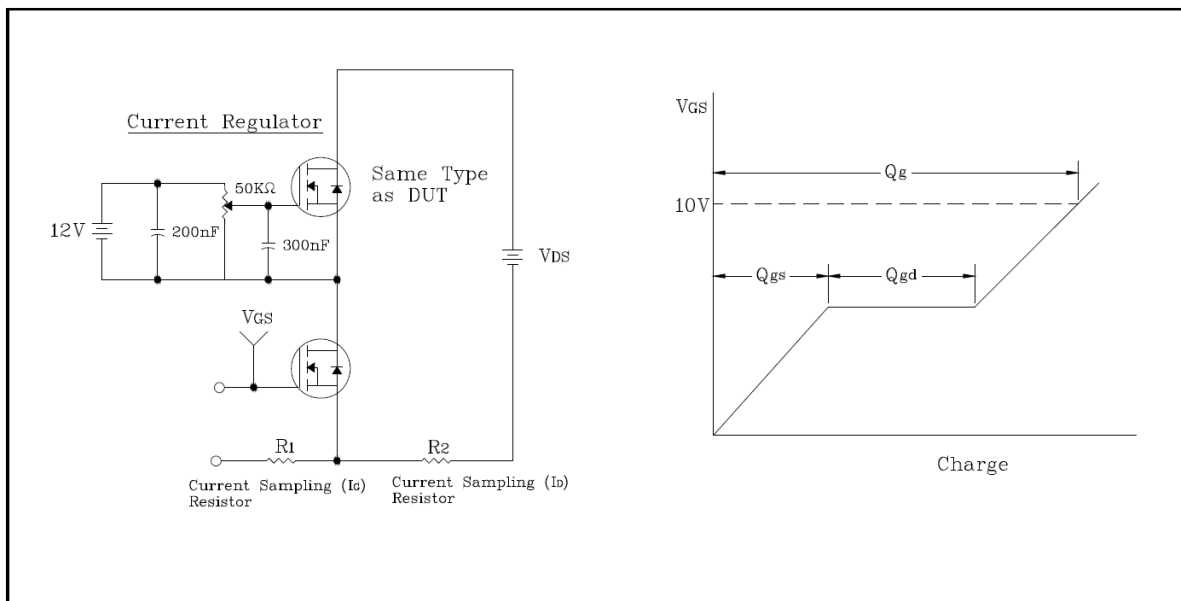


Fig. 12 Resistive Switching Test Circuit & Waveform

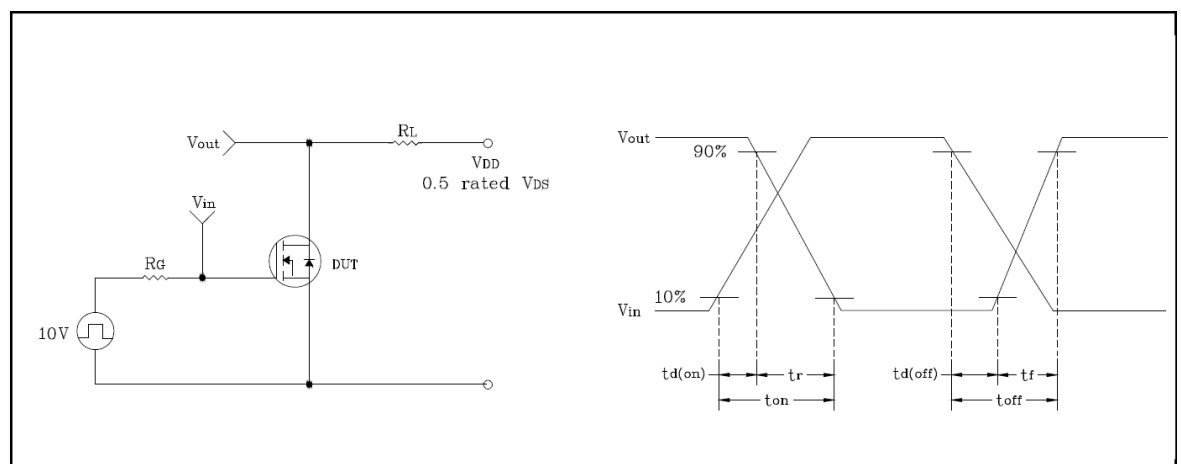


Fig. 13 EAS Test Circuit & Waveform

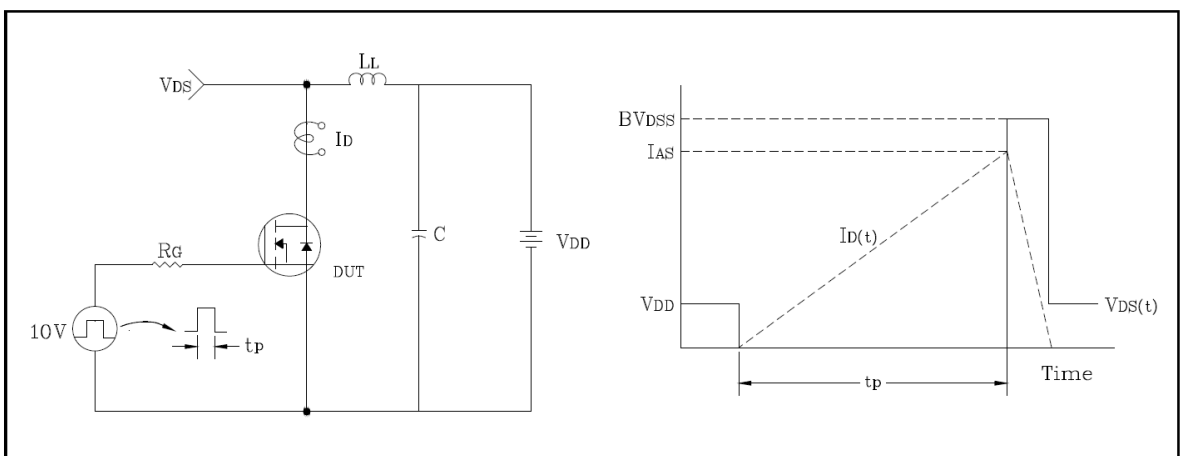
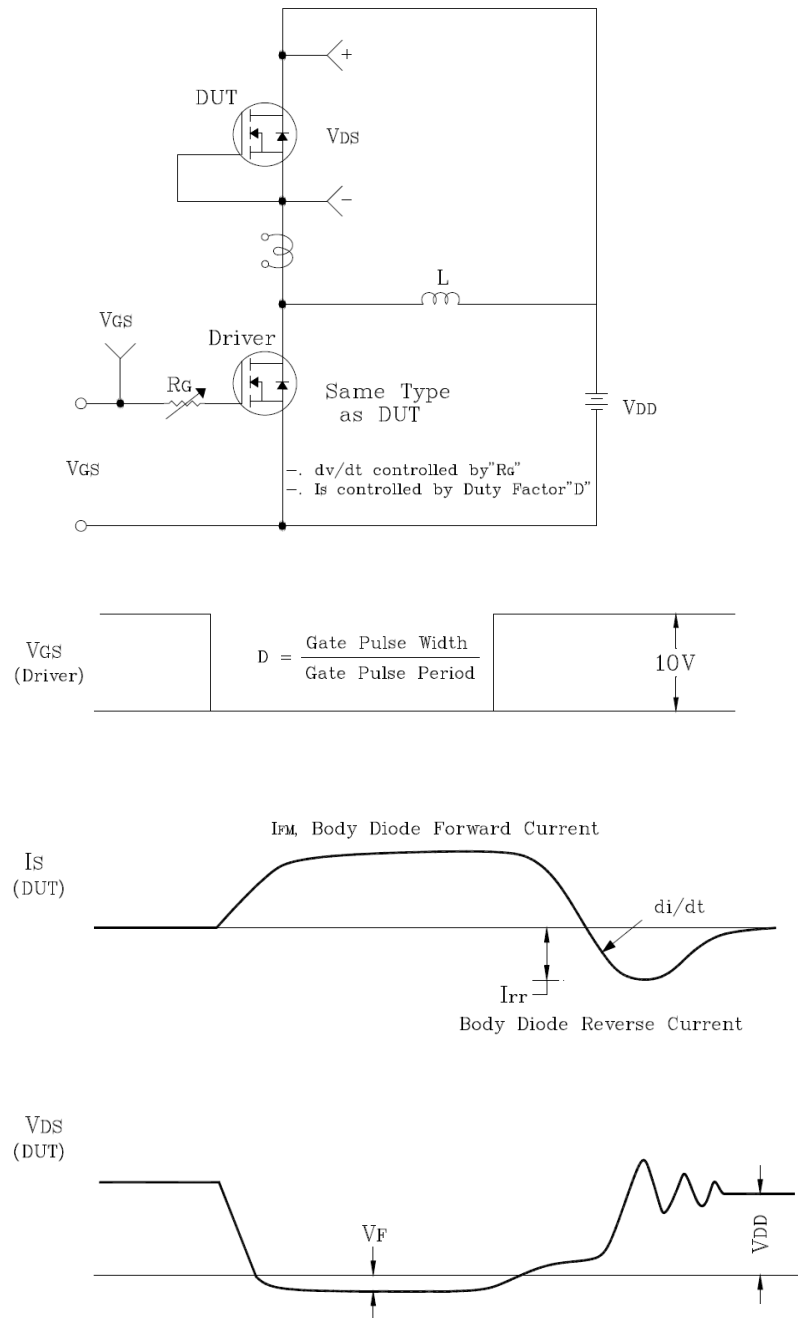


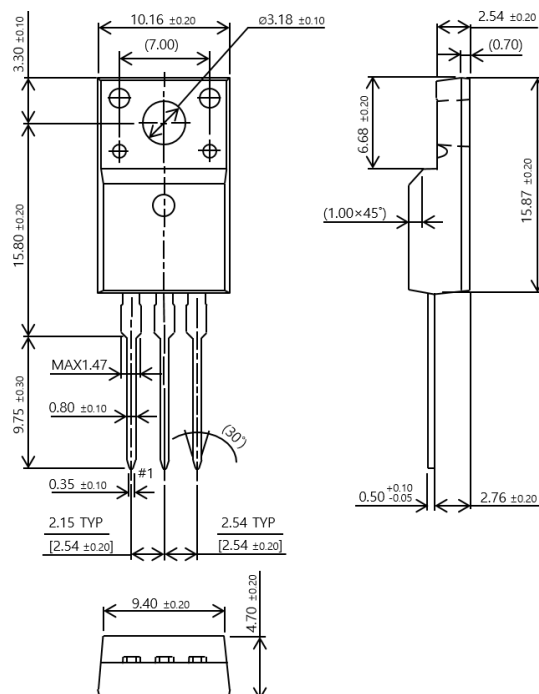


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform

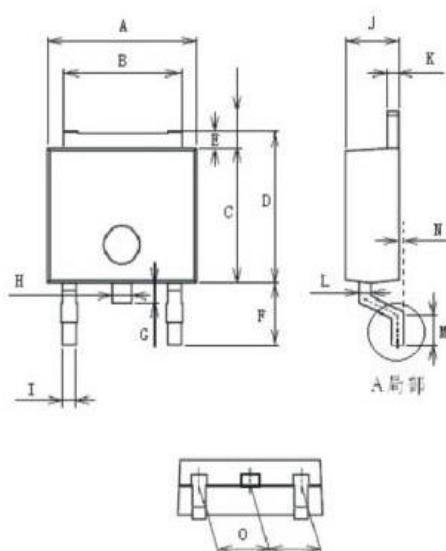


Package Dimensions

TO-220F



TO-252



Unit: mm

Item	Min	Max
A	6.40	6.70
B	5.20	5.40
C	6.00	6.30
D	6.55	6.85
E	0.45	0.60
F	3.07	3.35
G	0.85	1.05
H	0.75	0.95
I	0.55	0.75
J	2.20	2.40
K	0.43	0.58
L	0.43	0.58
M	0.90	1.10
N	0.90	1.10
O	2.20	2.40

Revision History

No	Date	Contents
0	2016-10-10	Initial Brief Datasheet Release
1	2019-01-11	Capacitance Update

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